

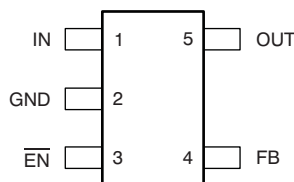
Low Output, Adjustable, Ultralow-Power, 100-mA Low-Dropout Linear Regulator

Check for Samples: [TPS76201-Q1](#)

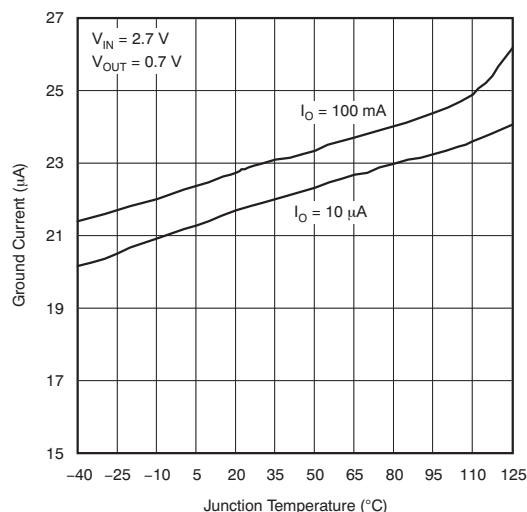
FEATURES

- Qualified for Automotive Applications
- 100-mA Low-Dropout Regulator
- Adjustable Output Voltage: 0.7 V to 5.5 V
- Only 27- μ A Quiescent Current at 100 mA
- 1- μ A Quiescent Current in Standby Mode
- Overcurrent Limitation
- -40°C to $+125^{\circ}\text{C}$ Operating Ambient Temperature Range
- Available in 5-Pin SOT-23 (DBV) Package

DBV PACKAGE (TOP VIEW)



GROUND CURRENT vs JUNCTION TEMPERATURE



DESCRIPTION

The TPS76201-Q1 low-dropout (LDO) voltage regulator features an adjustable output voltage as low as 0.7 V. It is an ideal regulator for sub 1.2-V DSP core voltage supplies and is equally suited for similar applications with other low-voltage processors and controllers. SOT-23 packaging and the high-efficiency that results from the ultralow power regulator operation make the TPS76201-Q1 especially useful in handheld and portable battery applications. This regulator features low dropout voltages and ultralow quiescent current compared to conventional LDO regulators. Offered in a five-terminal, small outline integrated circuit (SOT-23) package, the TPS76201-Q1 is ideal for micropower operations and where board space is at a premium.

A combination of new circuit design and process innovation has enabled the usual PNP pass transistor to be replaced by a PMOS pass element. Because the PMOS pass element is a voltage-driven device, the quiescent current is ultralow (30 μ A maximum) and is stable over the entire range of output load current (10 μ A to 100 mA). Intended for use in portable systems such as laptops and cellular phones, the ultralow-power operation results in a significant increase in the system battery operating life.

The TPS76201-Q1 also features a logic-enabled sleep mode to shut down the regulator, reducing quiescent current to 1 μ A typical at $T_J = +25^{\circ}\text{C}$. The TPS76201-Q1 is offered in an adjustable version (programmable over the range of 0.7 V to 5.5 V).



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION⁽¹⁾

VOLTAGE ⁽²⁾	T _A	PACKAGE	PART NUMBER	PACKAGE MARKING	TRANSPORT MEDIA, QUANTITY
Variable 0.7 V to 5.5 V	–40°C to +125°C	SOT-23 (DBV)	TPS76201QDBVRQ1	PUEQ	Tape and reel, 3000

- (1) For the most current package and ordering information see the Package Option Addendum at the end of this document, or visit the device product folder at www.ti.com.
 (2) Contact the factory for availability of fixed output options.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Over operating free-air temperature range (unless otherwise noted).

PARAMETER	TPS76201-Q1	UNIT
Input voltage range, V _{IN} ⁽²⁾	–0.3 to +13.5	V
Voltage range at $\overline{\text{EN}}$	–0.3 to V _{IN} +0.3	V
Voltage on OUT, FB	7	V
Peak output current, I _{OUT}	Internally limited	
Operating ambient temperature range, T _A	–40 to +150	°C
Storage temperature range, T _{STG}	–65 to +150	°C

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied..
 (2) All voltage values are with respect to network ground terminal.

THERMAL INFORMATION

THERMAL METRIC ⁽¹⁾		TPS76201-Q1	UNITS
		DBV	
		5 PINS	
θ _{JA}	Junction-to-ambient thermal resistance	183.6	°C/W
θ _{JC(top)}	Junction-to-case(top) thermal resistance	69.9	
θ _{JB}	Junction-to-board thermal resistance	41.6	
ψ _{JT}	Junction-to-top characterization parameter	2.4	
ψ _{JB}	Junction-to-board characterization parameter	40.9	
θ _{JC(bottom)}	Junction-to-case(bottom) thermal resistance	—	

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](http://www.ti.com/lit/an/spra953).

RECOMMENDED OPERATING CONDITIONS

Over operating free-air temperature range (unless otherwise noted).

	MIN	NOM	MAX	UNIT
Input voltage range, $V_{IN}^{(1)}$	2.7		10	V
Output voltage range, $V_{OUT}^{(2)}$	0.7		5.5	V
Continuous output current, $I_{OUT}^{(2)}$	0.01		100	mA
Operating ambient temperature range, $T_A^{(2)}$	–40		+125	°C

- (1) To calculate the minimum input voltage for the desired maximum output current, use the following formula: $V_{INmin} = V_{OUTmax} + V_{DO}$ (max load)
- (2) Continuous output current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.

ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range; $V_{IN} = V_{OUT(Typ)} + 1$ V; $I_{OUT} = 100$ mA, $\overline{EN} = 0$ V, and $C_{OUT} = 4.7$ μ F, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{OUT}	10-μA to 100-mA load ⁽¹⁾	0.7 V ≤ V _{OUT} ≤ 5.5 V, T _J = +25°C	V _{OUT}			V
		0.7 V ≤ V _{OUT} ≤ 5.5 V, T _J = -40°C to +125°C	0.97 × V _{OUT}	1.03 × V _{OUT}	V	
I _Q	GND current ⁽¹⁾⁽²⁾	$\overline{\text{EN}}$ = 0 V, 10 μA < I _{OUT} < 100 mA, T _J = +25°C	27			μA
		$\overline{\text{EN}}$ = 0 V, 10 μA < I _{OUT} < 100 mA, T _J = -40°C to +125°C	35			μA
	Load regulation	$\overline{\text{EN}}$ = 0 V, 10 μA < I _{OUT} < 100 mA, T _J = +25°C	12			mV
ΔV _O /V _{OUT}	Line regulation, output voltage ⁽²⁾	2.7 V < V _{IN} ≤ 10 V, T _J = +25°C, see ⁽¹⁾	0.04			%/V
		2.7 V < V _{IN} ≤ 10 V, T _J = -40°C to +125°C, see ⁽¹⁾	0.1			%/V
V _N	Output noise voltage	BW = 300 Hz to 50 kHz, C _{OUT} = 10 μF, V _{OUT} = 0.7 V, T _J = +25°C	60			μV _{RMS}
I _{CL}	Output current limit	V _{OUT} = 0 V, see ⁽¹⁾	350	750		mA
I _{STBY}	Standby current	$\overline{\text{EN}}$ = V _{IN} , 2.7 V < V _{IN} ≤ 10 V	1			μA
		T _J = -40°C to +125°C	2			μA
V _{EN(HI)}	High-level enable input voltage	2.7 V < V _{IN} ≤ 10 V	1.7			V
V _{EN(LO)}	Low-level enable input voltage	2.7 V < V _{IN} ≤ 10 V			0.8	V
PSRR	Power-supply rejection ratio	f = 1 kHz, C _{OUT} = 10 μF, T _J = +25°C, see ⁽¹⁾	60			dB
I _{EN}	Enable pin current	$\overline{\text{EN}}$ = 0 V	-1	0	1	μA
		$\overline{\text{EN}}$ = V _{IN}	-1		1	μA

- (1) Minimum IN operating voltage is 2.7 V or $V_{OUT(typ)} + 1$ V, whichever is greater. Maximum IN voltage = 10 V, minimum output current = 10 μ A, and maximum output current = 100 mA.

- (2) If $V_{OUT} \leq 1.8$ V, then $V_{INmin} = 2.7$ V, $V_{INmax} = 10$ V: $\text{Line Reg. (mV)} = (\%/V) \times \frac{V_{OUT}(V_{Imax} - 2.7\text{ V})}{100} \times 1000$
If $V_{OUT} \geq 2.5$ V, then $V_{INmin} = V_{OUT} + 1$ V, $V_{INmax} = 10$ V: $\text{Line Reg. (mV)} = (\%/V) \times \frac{V_{OUT}[V_{Imax} - (V_{OUT} + 1\text{ V})]}{100} \times 1000$

FUNCTIONAL BLOCK DIAGRAM

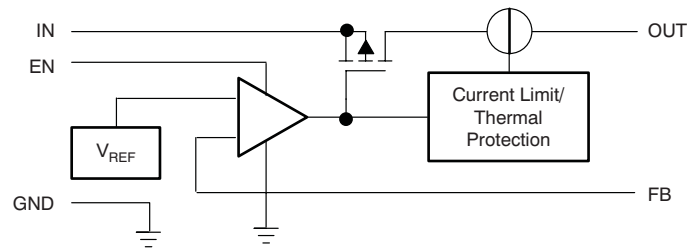
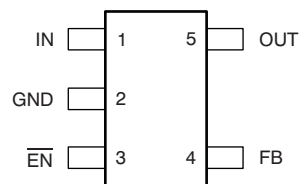


Figure 1. TPS76201-Q1

PIN CONFIGURATION

DBV PACKAGE
SOT-23
(TOP VIEW)



PIN DESCRIPTIONS

NAME	SOT-23 DBV	I/O	DESCRIPTION
IN	1	I	Input supply voltage
GND	2	—	Ground pin
$\overline{\text{EN}}$	3	I	Enable input
OUT	4	I	Regulated output voltage
FB	5	O	Feedback voltage

TYPICAL CHARACTERISTICS

At $T_J = -40^\circ\text{C}$ to $+125^\circ\text{C}$, $V_{IN} = V_{OUT(TYP)} + 0.5\text{ V}$ or 2.0 V , whichever is greater; $I_{OUT} = 10\text{ mA}$, $V_{EN} = V_{IN}$, $C_{OUT} = 1.0\text{ }\mu\text{F}$, unless otherwise noted. Typical values are at $T_J = +25^\circ\text{C}$.

**OUTPUT VOLTAGE vs
OUTPUT CURRENT**

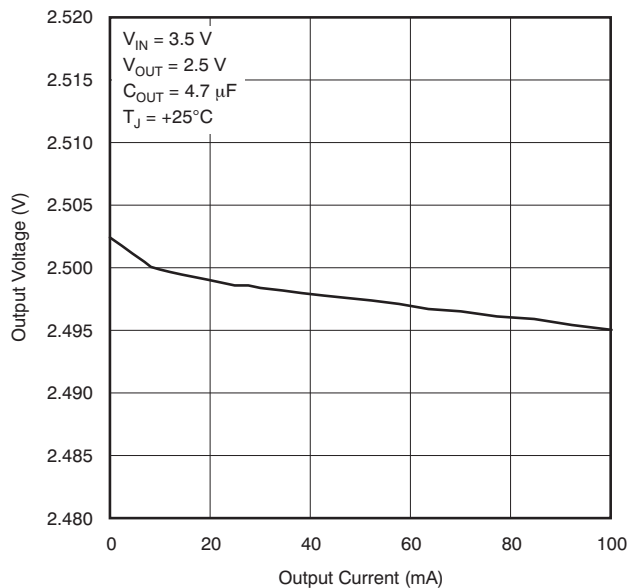


Figure 2.

**OUTPUT VOLTAGE vs
OUTPUT CURRENT**

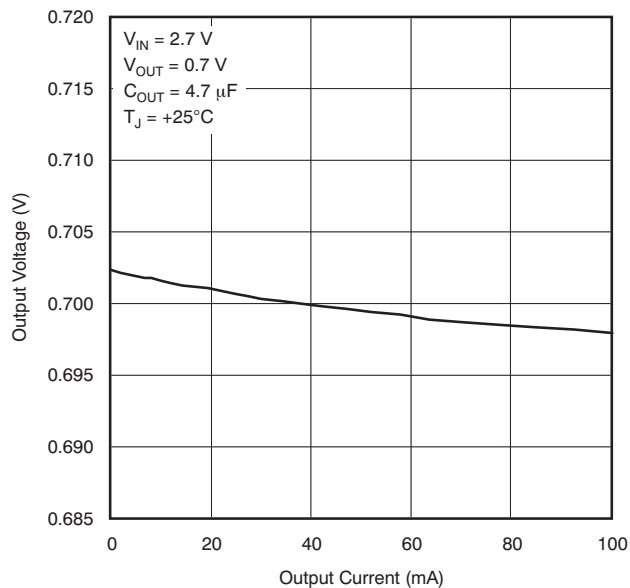


Figure 3.

**OUTPUT VOLTAGE vs
JUNCTION TEMPERATURE**

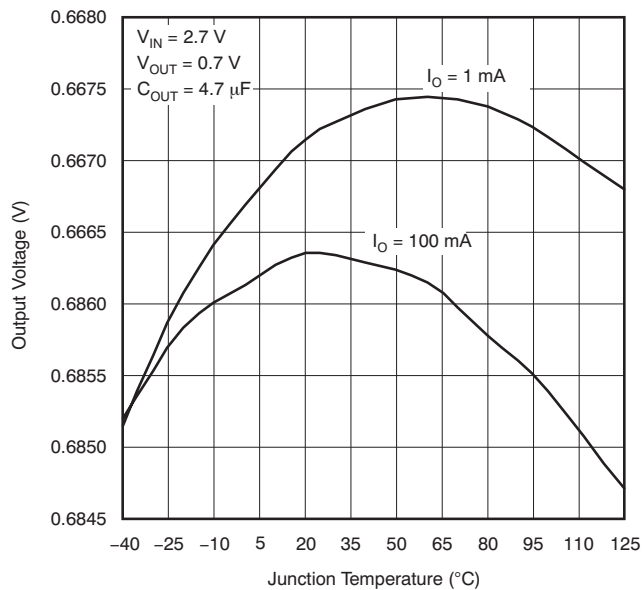


Figure 4.

**GROUND CURRENT vs
JUNCTION TEMPERATURE**

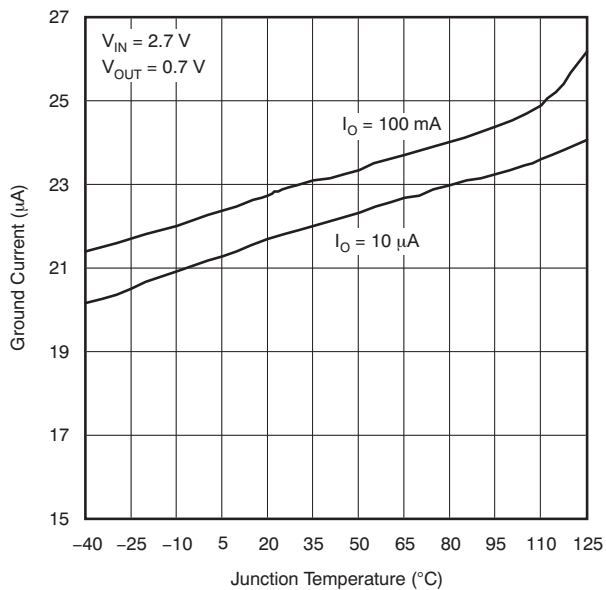


Figure 5.

TYPICAL CHARACTERISTICS (continued)

At $T_J = -40^\circ\text{C}$ to $+125^\circ\text{C}$, $V_{IN} = V_{OUT(TYP)} + 0.5\text{ V}$ or 2.0 V , whichever is greater; $I_{OUT} = 10\text{ mA}$, $V_{EN} = V_{IN}$, $C_{OUT} = 1.0\text{ }\mu\text{F}$, unless otherwise noted. Typical values are at $T_J = +25^\circ\text{C}$.

OUTPUT SPECTRAL NOISE DENSITY vs FREQUENCY

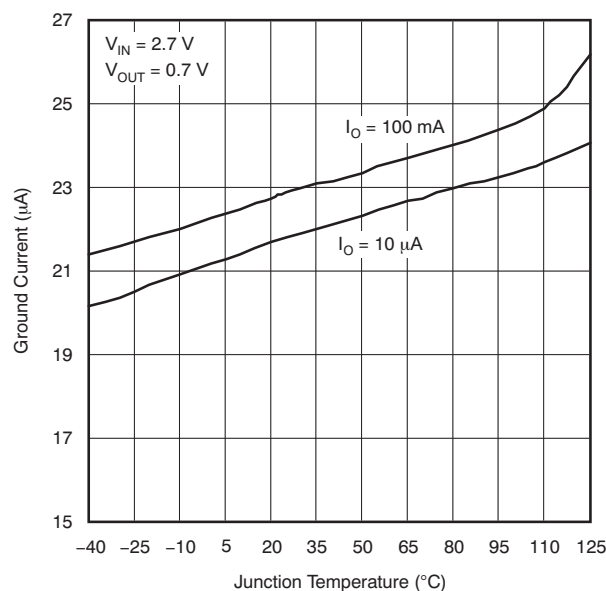


Figure 6.

OUTPUT IMPEDANCE vs FREQUENCY

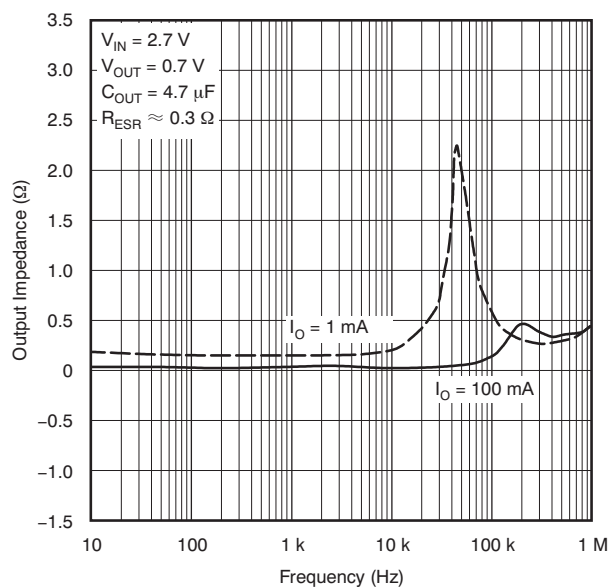


Figure 7.

**DROPOUT VOLTAGE vs
INPUT VOLTAGE**

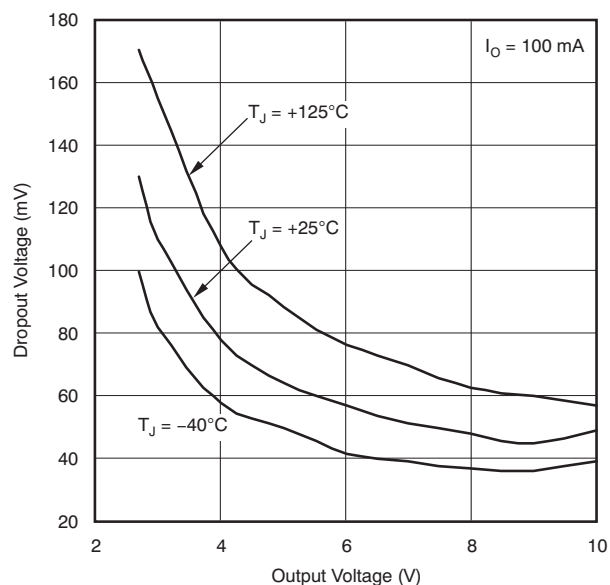


Figure 8.

**DROPOUT VOLTAGE vs
JUNCTION TEMPERATURE**

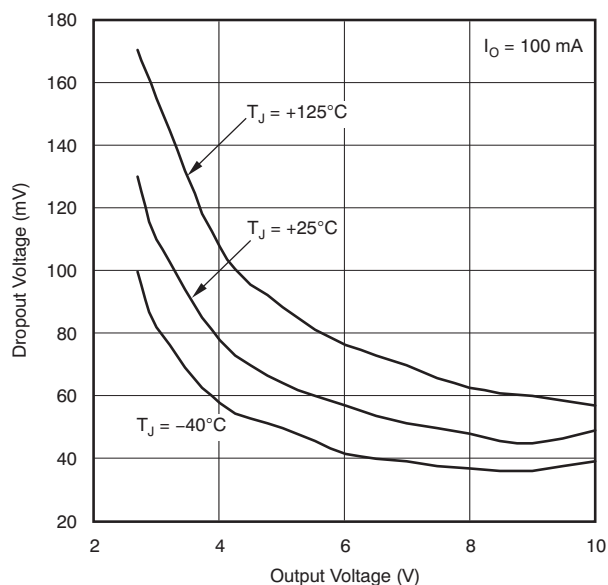


Figure 9.

TYPICAL CHARACTERISTICS (continued)

At $T_J = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $V_{IN} = V_{OUT(TYP)} + 0.5\text{ V}$ or 2.0 V , whichever is greater; $I_{OUT} = 10\text{ mA}$, $V_{EN} = V_{IN}$, $C_{OUT} = 1.0\text{ }\mu\text{F}$, unless otherwise noted. Typical values are at $T_J = +25^{\circ}\text{C}$.

POWER-SUPPLY RIPPLE REJECTION vs FREQUENCY

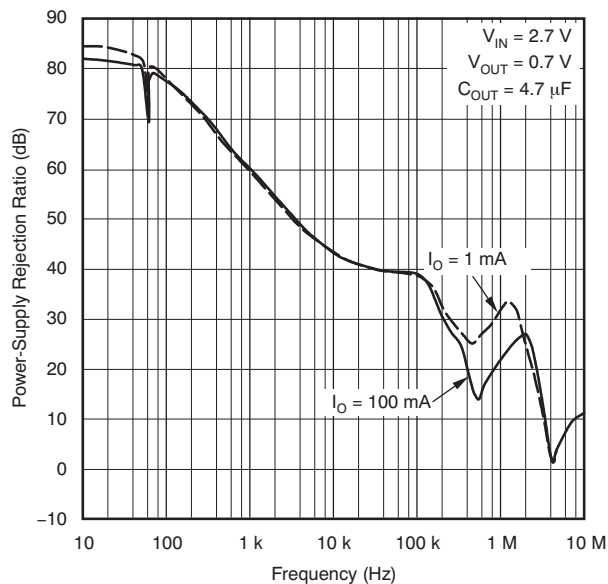


Figure 10.

**OUTPUT VOLTAGE AND ENABLE VOLTAGE
vs TIME (START-UP)**

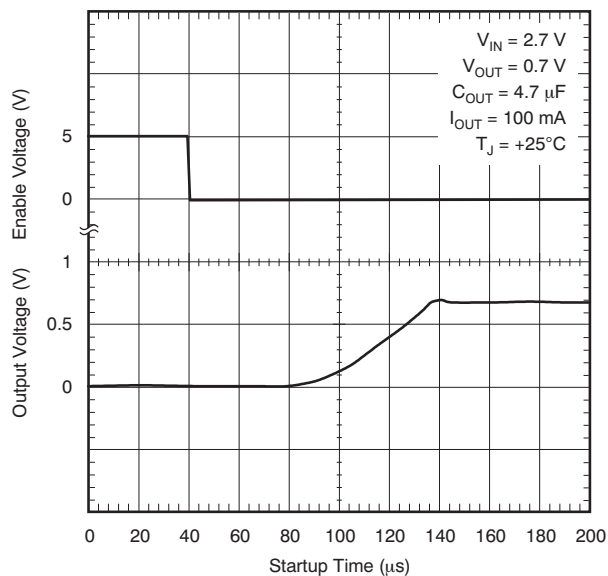


Figure 11.

LINE TRANSIENT RESPONSE

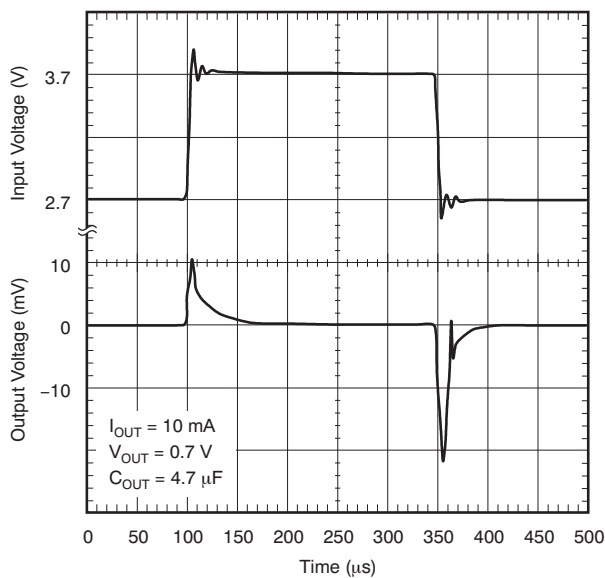


Figure 12.

LOAD TRANSIENT RESPONSE

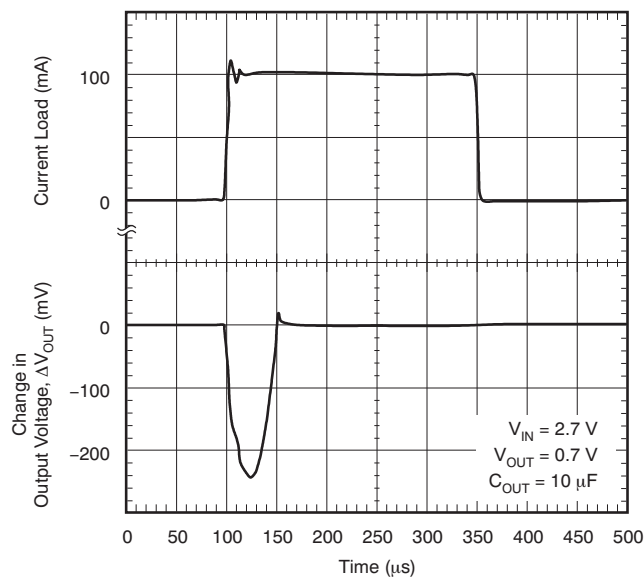


Figure 13.

TYPICAL CHARACTERISTICS (continued)

At $T_J = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $V_{IN} = V_{OUT(TYP)} + 0.5\text{ V}$ or 2.0 V , whichever is greater; $I_{OUT} = 10\text{ mA}$, $V_{EN} = V_{IN}$, $C_{OUT} = 1.0\text{ }\mu\text{F}$, unless otherwise noted. Typical values are at $T_J = +25^{\circ}\text{C}$.

LINE TRANSIENT RESPONSE

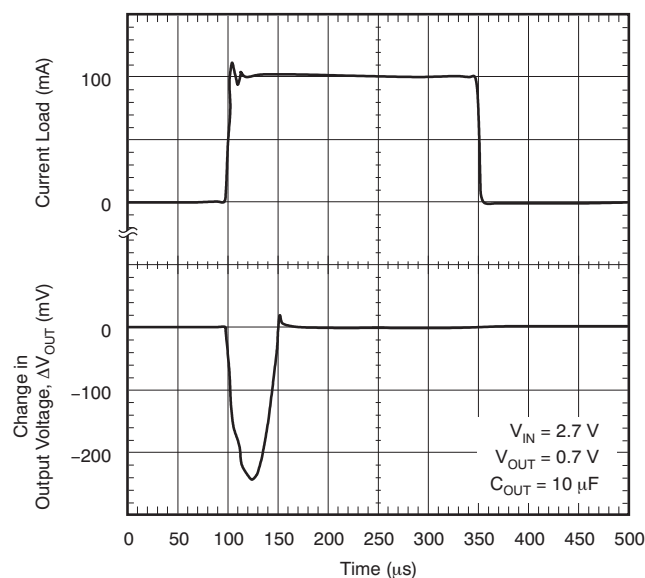


Figure 14.

LOAD TRANSIENT RESPONSE

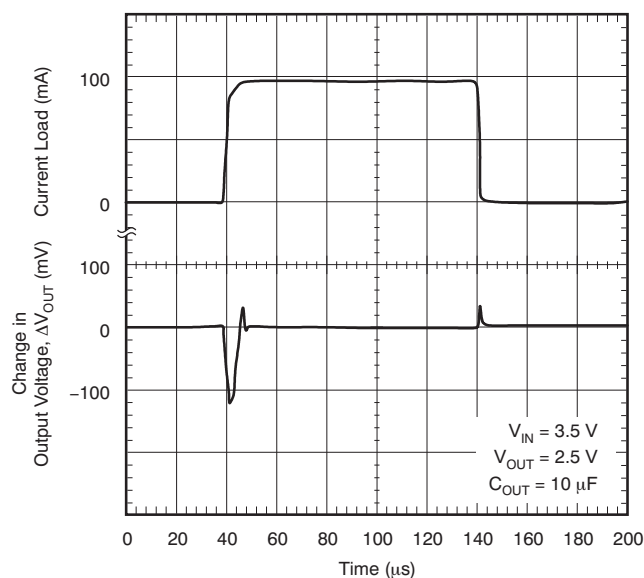


Figure 15.

TYPICAL REGIONS OF STABILITY EQUIVALENT SERIES RESISTANCE (ESR) vs OUTPUT CURRENT

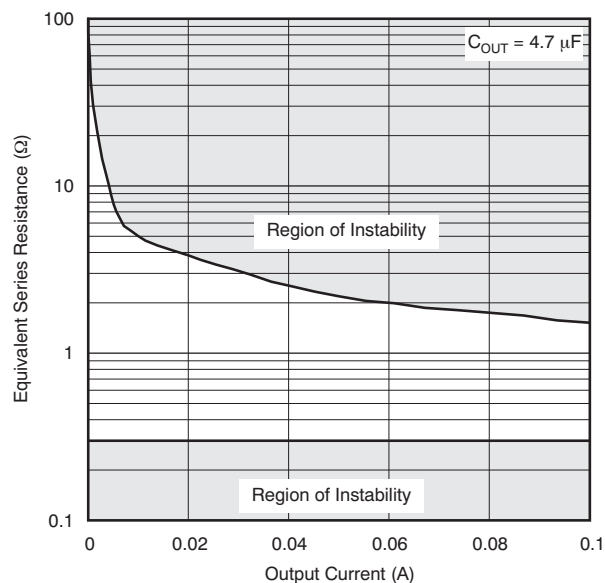


Figure 16.

TYPICAL REGIONS OF STABILITY EQUIVALENT SERIES RESISTANCE (ESR) vs OUTPUT CURRENT

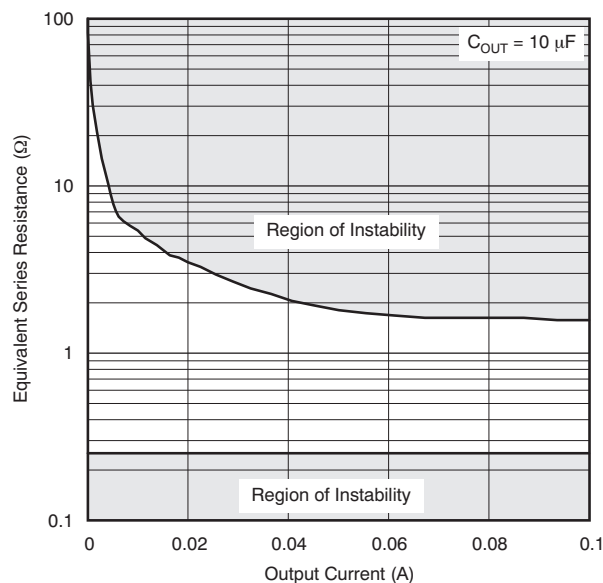


Figure 17.

APPLICATION INFORMATION

The TPS76201-Q1 low-dropout (LDO) regulator has been optimized for use in battery-operated equipment including, but not limited to, the sub 1.2-V DSP core voltage supplies. It features low quiescent current (23 μ A nominally) and enable inputs to reduce supply currents to 1 μ A when the regulators are turned off. A typical application circuit is shown in Figure 18.

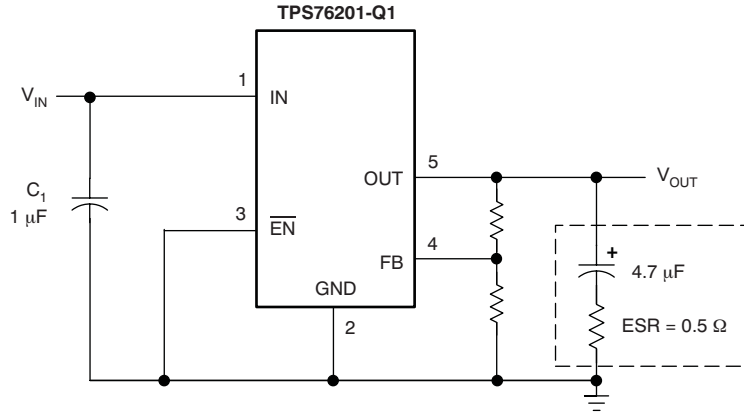


Figure 18. Typical Application Circuit

External Capacitor Requirements

Although not required, a 0.047- μ F or larger ceramic input bypass capacitor, connected between IN and GND and located close to the TPS76201-Q1, is recommended to improve transient response and noise rejection. A higher-value electrolytic input capacitor may be necessary if large, fast-rise-time load transients are anticipated and the device is located several inches from the power source.

Like all low dropout regulators, the TPS76201-Q1 requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance is 4.7 μ F. The equivalent series resistance (ESR) of the capacitor should be between 0.3 Ω and 1.5 Ω to ensure stability. Capacitor values larger than 4.7 μ F are acceptable, and allow the use of smaller ESR values. Capacitors less than 4.7 μ F are not recommended because they require careful selection of ESR to ensure stability. Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Most of the commercially available 4.7- μ F surface-mount solid tantalum capacitors, including devices from Sprague, Kemet, and Nichico, meet these ESR requirements. Multilayer ceramic capacitors may have very small equivalent series resistances and therefore may require the addition of a low-value series resistor to ensure stability. Table 1 summarizes the capacitor selection recommendations.

Table 1. Capacitor Selection

PART NO.	MFR	VALUE	MAX ESR ⁽¹⁾	SIZE (H x L x W) ⁽²⁾
T494B475K016AS	KEMET	4.7 μ F	1.5 Ω	1.9 x 3.5 x 2.8
195D106x0016x2T	SPRAGUE	10 μ F	1.5 Ω	1.3 x 7.0 x 2.7
695D106x003562T	SPRAGUE	10 μ F	1.3 Ω	2.5 x 7.6 x 2.5
TPSC475K035R0600	AVX	4.7 μ F	0.6 Ω	2.6 x 6.0 x 3.2

(1) ESR is maximum resistance in Ohms at 100 kHz and $T_A = +25^\circ\text{C}$. Contact manufacturer for minimum ESR values.

(2) Size is shown in mm.

Output Voltage Programming

The output voltage of the TPS76201-Q1 adjustable regulator is programmed using an external resistor divider as shown in [Figure 19](#). The output voltage is calculated using:

$$V_{OUT} = V_{REF} \times \left(1 + \frac{R1}{R2}\right) \quad (1)$$

Where:

$$V_{REF} = 0.6663 \text{ V, typ (the internal reference voltage)}$$

Resistors R1 and R2 should be chosen for approximately 10-μA divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided because leakage currents at FB increase the output voltage error. The recommended design procedure is to choose R2 = 66.5 kΩ to set the divider current at 10 μA and then calculate R1 using [Equation 2](#):

$$R1 = \left(\frac{V_{OUT}}{V_{REF}} - 1\right) \times R2 \quad (2)$$

**OUTPUT VOLTAGE
PROGRAMMING GUIDE**

OUTPUT VOLTAGE (V)	DIVIDER RESISTANCE (kΩ) ⁽¹⁾	
	R1	R2
0.7	3.36	66.5
0.9	23.2	66.5
1.2	53.6	66.5
1.5	83.5	66.5
1.8	113	66.5
2.5	182	66.5
3.3	246	66.5
3.6	294	66.5
4	332	66.5
5	432	66.5

(1) 1% values shown.

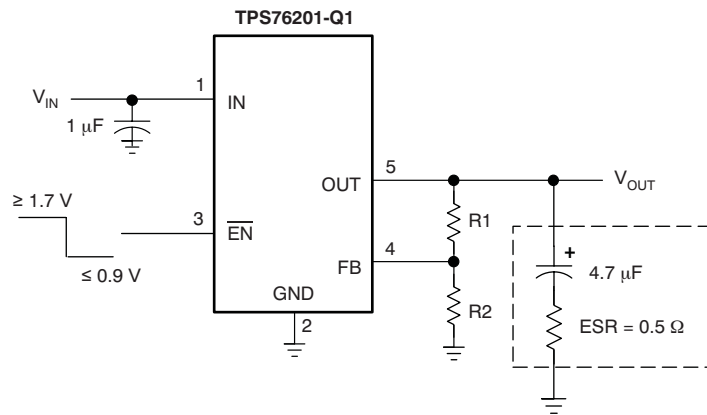


Figure 19. TPS76201-Q1 Adjustable LDO Regulator Programming

Power Dissipation and Junction Temperature

Specified regulator operation is assured to a junction temperature of +125°C; the maximum junction temperature should be restricted to +150°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, $P_{D(max)}$, and the actual dissipation, P_D , which must be less than or equal to $P_{D(max)}$.

The maximum power dissipation limit is determined using [Equation 3](#):

$$P_{D(max)} = \frac{T_{J(max)} - T_A}{R_{\theta JA}} \quad (3)$$

Where:

T_{Jmax} is the maximum allowable junction temperature.

$R_{\theta JA}$ is the thermal resistance junction-to-ambient for the package; see the [Thermal Information](#) table.

T_A is the ambient temperature.

The regulator dissipation is calculated using [Equation 4](#):

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} \quad (4)$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation triggers the thermal protection circuit.

Regulator Protection

The TPS76201-Q1 PMOS-pass transistor has a built-in back diode that conducts reverse current when the input voltage drops below the output voltage (for example, during power down). Current is conducted from the output to the input and is not internally limited. If extended reverse voltage operation is anticipated, external limiting might be appropriate.

The TPS76201-Q1 features internal current limiting and thermal protection. During normal operation, the TPS76201-Q1 limits output current to approximately 350 mA. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds approximately +165°C, thermal protection circuitry shuts it down. Once the device has cooled to below approximately +140°C, regulator operation resumes.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS76201QDBVRQ1	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	PUEQ
TPS76201QDBVRQ1.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	PUEQ

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF TPS76201-Q1 :

- Catalog : [TPS76201](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS76201QDBVRQ1	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS76201QDBVRQ1	SOT-23	DBV	5	3000	200.0	183.0	25.0

EXAMPLE BOARD LAYOUT

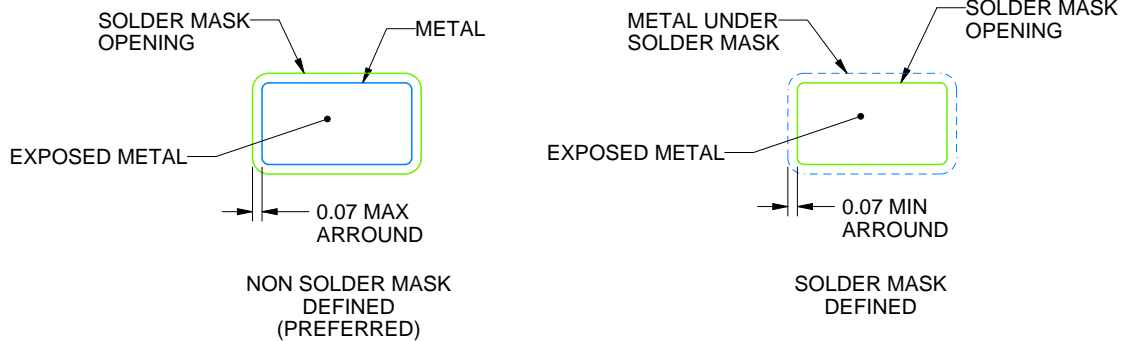
DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214839/K 08/2024

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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